

Extreme Low Loss and High Thermal
Reliability Laminate and Prepreg



tuc 台燿科技

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Delivering Value through Innovation and Dedication



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ThunderClad 5N_TU-953N

Core: TU-953N

Prepreg: TU-953P N

TU-953N is an advanced material designed for high speed computing, telecommunications, radio frequency super low loss filed applications. **TU-953N** electrical performance is competitive with PTFE-based, hydrocarbon-based very low loss materials, but capable for high layer count circuit board design with excellent thermal reliability.

TU-953N laminates also exhibit excellent moisture resistance, improved CTE, superior chemical resistance, thermal stability, CAF resistance, and also compatible with modified FR-4 processes.

Applications

- AI Servers, Networking
- Backplane, High performance computing
- Line cards, Storage
- Servers, Telecom, Base station
- Office Routers

Performance and Processing Advantages

- Excellent electrical and thermal properties
- Dielectric constant is 3.21 @ 10GHz
- Dissipation factor is 0.00113 @ 10GHz
- Stable and flat Dk/Df performance over frequency and temperature variance.
- Compatible with modified FR-4 processes
- Excellent moisture resistance and Lead Free reflow process compatible
- Improved z-axis thermal expansion
- Superior dimensional stability, thickness uniformity and flatness
- Anti-CAF capability
- Excellent through-hole and soldering reliability
- Halogen Free

Industry Approvals

- IPC-4101E Specification Number : /134
- UL File Number: E189572
- ANSI Grade: No-ANSI
- Flammability Rating: 94V-0
- Maximum Operating Temperature: 170°C

Standard Availability

- Thickness: 0.002" [0.05mm] to 0.028" [0.71mm], available in sheet or panel form
- Copper Foil Cladding: 1/3 to 2 oz for built-up & double sides
- Prepregs: Available in roll or panel form
- Glass Styles: 1035, 1078, 2116 and other prepreg grades are available upon request

The newly developed products are slightly modified and updated after more data has been collected.



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DS2603001A



	Typical Values	Conditioning
Thermal		
Tg (DMA)	200 °C	E-2/105
Td (TGA)	430 °C	
CTE x/y axis	7/8 ppm/°C	E-2/105
CTE z-axis α1	40 ppm/°C	
CTE z-axis α2	150 ppm/°C	
CTE z-axis	1.5%	
Thermal Stress, Solder Float, 288°C	> 120 sec	A
T-260	> 60 min	E-2/105
T-288	> 60 min	
T-300	> 60 min	
Flammability	94V-0	E-24/125
Electrical		
Permittivity (RC70%) 10 GHz (SCR method)	3.21	E-2/105
Loss Tangent (RC70%) 10 GHz (SCR method)	0.00113	E-2/105
Volume Resistivity	> 10 ¹⁰ MΩ·cm	C-96/35/90
Surface Resistivity	> 10 ⁸ MΩ	C-96/35/90
Electric Strength	> 40 KV/mm	A
Dielectric Breakdown Voltage	> 50 KV	A
Mechanical		
Young's Modulus Warp Direction	23 GPa	A
Fill Direction	22 GPa	
Flexural Strength Lengthwise	> 60,000 psi	A
Crosswise	> 50,000 psi	
Peel Strength, H oz HVLP Cu foil	2~3 lb/in	A
Moisture Absorption	0.03 %	E-1/105 + D-24/23

NOTE:

1. Property values are for information purposes only and not intended for specification.
2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.
3. This product is based on a patent pending technology.

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